Specification of Thermoelectric Module

TEC1-12724

Description

The 127 couples, 55 mm \times 55 mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

Performance Specification Sheet

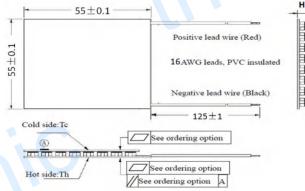
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂
DT _{max} (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U _{max} (Voltage)	16.0	17.2	Voltage applied to the module at DT _{max}
I _{max} (amps)	21	21	DC current through the modules at DT _{max}
Q _{Cmax} (Watts)	210.4	229.8	Cooling capacity at cold side of the module under $DT = 0$ °C
AC resistance (ohms)	0.58	0.62	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

A Soldon

Geometric Characteristics Dimensions in millimeters



Ordering Option

Manufacturing Options

A. Solder:	B. Sealant:
1. T100: BiSn (Tmelt=138°C)	1. NS: No sealing (Standard)
2. T200: CuAgSn (Tmelt = 217°C)	2. SS: Silicone sealant
3. T240: SbSn (Tmelt = 240°C)	3. EPS: Epoxy sealant
C. Ceramics:	D. Ceramics Surface Options:

- 1. Alumina (Al₂O₃, white 96%)
- 2. Aluminum Nitride (AlN)

IN) 2. Metalized Naming for the Module

1. Blank ceramics (not metalized)

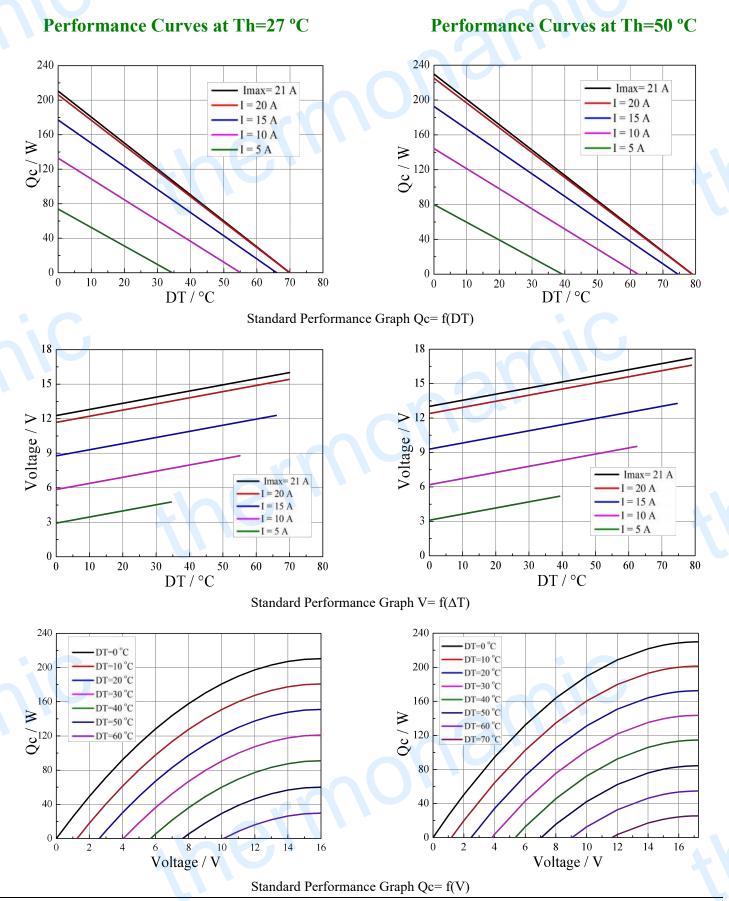
D Soolant

Suffix Thickness Flatness/ Parallelis (mm) (mm)		Flatness/ Parallelism	Lead wire length(mm)	TEC1-12724- $\mathbf{X} - \mathbf{X} - \mathbf{X}$	
		(mm)	Standard/Optional length		
TF	0:4.05±0.1	0:0.1/0.1	125±1/Specify	Flatness/Parallelism Sealant Solder	
TF	1:4.05±0.05	1:0.05/0.05	125±1/Specify	TEC1-12724-T100 -NS –TF00 -AlO T100: BiSn(Tmelt=138°C)	
Eg. TF00: Thickness 4.05 ± 0.1 (mm) and Flatness $0.1 / 0.1$ (mm)				NS: No sealing AlO: Alumina (Al2O3, white 96%) TF00: Thickness±0.1(mm) and Flatness/Parallelism:0.05/0.05(mm)	

Creative technology with fine manufacturing processes provides you the reliable and quality products Tel: +86-791-88198288 Fax: +86-791-88198308 Email: <u>sales@thermonamic.com.cn</u> Web Site: www.thermonamic.com.cn

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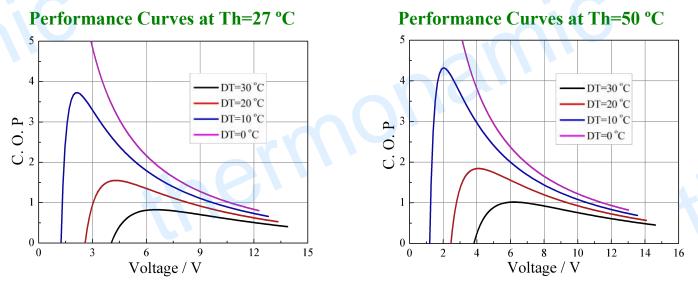
TEC1-12724



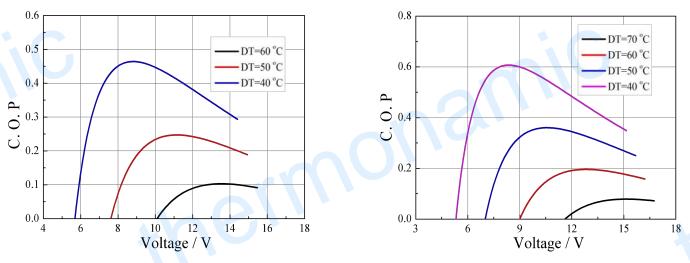
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Standard Performance Graph COP = f(V) of ΔT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of ΔT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating msnc
- Storage module below 100 °C
- Operation below I_{max} or V_{max}
- Work under DC